



## Material Content Data Sheet



Sales Product Name	BTM7710GP			Issued		29. August 2013		
MA#	MA000303870							
Package	PG-TO263-15-1			Weight*		3410.64 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	10.397	0.30	0.30	3048	3048
leadframe	non noble metal	iron	7439-89-6	2.037	0.06		597	
	inorganic material	phosphorus	7723-14-0	0.611	0.02		179	
	non noble metal	copper	7440-50-8	2034.173	59.64	59.72	596420	597196
wire	non noble metal	aluminium	7429-90-5	1.980	0.06	0.06	581	581
encapsulation	organic material	carbon black	1333-86-4	19.810	0.58		5808	
	plastics	epoxy resin	-	217.915	6.39		63893	
	inorganic material	silicondioxide	60676-86-0	1082.971	31.75	38.72	317527	387228
leadfinish	non noble metal	tin	7440-31-5	31.059	0.91	0.91	9106	9106
plating	non noble metal	nickel	7440-02-0	0.493	0.01		145	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	0	145
solder	noble metal	silver	7440-22-4	0.230	0.01		67	
	non noble metal	tin	7440-31-5	0.184	0.01		54	
	non noble metal	lead	7439-92-1	8.781	0.26	0.28	2575	2696
*deviation	< 10%	Sum in total:			100,00		1000000	

### Important Remarks:

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